

L Number	Hits	Search Text	DB	Time stamp
1	2856	(((((conduct\$3 copper) near5 (foil sheet layer)) and (etch\$3 pattern\$4)) and (via trench hole recess)) and (insulat\$3 dielectric)) and (pr photo?resist photoresist resist)) and (copper Cu aluminum Al)) and wir\$3) and resin) and circuit) and (cover\$3 encapsulat\$3)) and ((etch\$3 pattern\$4) near10 (copper Cu conduct\$3))) and wir\$3) and (die bond\$3)	USPAT; US-PGPUB	2003/04/29 18:26
2	5	(((((conduct\$3 copper) near5 (foil sheet layer)) and (etch\$3 pattern\$4)) and (via trench hole recess)) and (insulat\$3 dielectric)) and (pr photo?resist photoresist resist)) and (copper Cu aluminum Al)) and wir\$3) and resin) and circuit) and (cover\$3 encapsulat\$3)) and ((etch\$3 pattern\$4) near10 (copper Cu conduct\$3))) and wir\$3) and (die bond\$3)	EPO; JPO; DERWENT; IBM_TDB	2003/04/29 18:27
3	5	(((((conduct\$3 copper) near5 (foil sheet layer plate)) and (etch\$3 pattern\$4)) and (via trench hole recess)) and (insulat\$3 dielectric)) and (pr photo?resist photoresist resist)) and (copper Cu aluminum Al)) and wir\$3) and resin) and circuit) and (cover\$3 encapsulat\$3)) and ((etch\$3 pattern\$4) near10 (copper Cu conduct\$3))) and wir\$3) and (die bond\$3)	EPO; JPO; DERWENT; IBM_TDB	2003/04/29 18:28
4	2908	(((((conduct\$3 copper) near5 (foil sheet layer plate)) and (etch\$3 pattern\$4)) and (via trench hole recess)) and (insulat\$3 dielectric)) and (pr photo?resist photoresist resist)) and (copper Cu aluminum Al)) and wir\$3) and resin) and circuit) and (cover\$3 encapsulat\$3)) and ((etch\$3 pattern\$4) near10 (copper Cu conduct\$3))) and wir\$3) and (die bond\$3)	USPAT; US-PGPUB	2003/04/29 18:29
5	52	(((((conduct\$3 copper) near5 (foil sheet layer plate)) and (etch\$3 pattern\$4)) and (via trench hole recess)) and (insulat\$3 dielectric)) and (pr photo?resist photoresist resist)) and (copper Cu aluminum Al)) and wir\$3) and resin) and circuit) and (cover\$3 encapsulat\$3)) and ((etch\$3 pattern\$4) near10 (copper Cu conduct\$3))) and wir\$3) and (die bond\$3)) not (((((conduct\$3 copper) near5 (foil sheet layer)) and (etch\$3 pattern\$4)) and (via trench hole recess)) and (insulat\$3 dielectric)) and (pr photo?resist photoresist resist)) and (copper Cu aluminum Al)) and wir\$3) and resin) and circuit) and (cover\$3 encapsulat\$3)) and ((etch\$3 pattern\$4) near10 (copper Cu conduct\$3))) and wir\$3) and (die bond\$3))	USPAT; US-PGPUB	2003/04/29 18:30
-	12192	conduct\$3 near5 foil	USPAT; US-PGPUB	2003/02/11 15:12
-	4707	(conduct\$3 near5 foil) and resin	USPAT; US-PGPUB	2003/02/11 12:50
-	3142	((conduct\$3 near5 foil) and resin) and (pattern\$5 etch\$3)	USPAT; US-PGPUB	2003/02/11 12:51
-	2706	((conduct\$3 near5 foil) and resin) and (pattern\$5 etch\$3)) and (insulat\$3 dielectric)	USPAT; US-PGPUB	2003/02/11 12:51
-	2530	((conduct\$3 near5 foil) and resin) and (pattern\$5 etch\$3)) and (insulat\$3 dielectric)) and (via hole recess contact)	USPAT; US-PGPUB	2003/02/11 12:53

-	968	(((((conduct\$3 near5 foil) and resin) and (pattern\$5 etch\$3)) and (insulat\$3 dielectric)) and (via hole recess contact)) and (pr resist)	USPAT; US-PGPUB	2003/02/11 12:53
-	755	(((((conduct\$3 near5 foil) and resin) and (pattern\$5 etch\$3)) and (insulat\$3 dielectric)) and (via hole recess contact)) and (pr resist)	USPAT	2003/02/11 12:54
-	445	multilayer\$3 near3 wir\$3 near3 circuit	USPAT; US-PGPUB	2003/02/11 13:02
-	183779	(conduct\$3 copper) near5 (foil sheet layer)	USPAT; US-PGPUB	2003/02/11 15:16
-	111368	((conduct\$3 copper) near5 (foil sheet layer)) and (etch\$3 pattern\$4)	USPAT; US-PGPUB	2003/02/11 15:18
-	80228	((conduct\$3 copper) near5 (foil sheet layer)) and (etch\$3 pattern\$4)) and (via trench hole recess)	USPAT; US-PGPUB	2003/02/11 15:30
-	67836	(((((conduct\$3 copper) near5 (foil sheet layer)) and (etch\$3 pattern\$4)) and (via trench hole recess)) and (insulat\$3 dielectric)	USPAT; US-PGPUB	2003/02/11 15:31
-	30233	(((((conduct\$3 copper) near5 (foil sheet layer)) and (etch\$3 pattern\$4)) and (via trench hole recess)) and (insulat\$3 dielectric)) and (pr photo?resist photoresist resist)	USPAT; US-PGPUB	2003/02/11 15:32
-	28811	((((((conduct\$3 copper) near5 (foil sheet layer)) and (etch\$3 pattern\$4)) and (via trench hole recess)) and (insulat\$3 dielectric)) and (pr photo?resist photoresist resist)) and (copper Cu aluminum Al)	USPAT; US-PGPUB	2003/02/11 15:34
-	13674	((((((conduct\$3 copper) near5 (foil sheet layer)) and (etch\$3 pattern\$4)) and (via trench hole recess)) and (insulat\$3 dielectric)) and (pr photo?resist photoresist resist)) and (copper Cu aluminum Al)) and wir\$3	USPAT; US-PGPUB	2003/02/11 15:35
-	5322	((((((conduct\$3 copper) near5 (foil sheet layer)) and (etch\$3 pattern\$4)) and (via trench hole recess)) and (insulat\$3 dielectric)) and (pr photo?resist photoresist resist)) and (copper Cu aluminum Al)) and wir\$3 and resin	USPAT; US-PGPUB	2003/02/11 15:39
-	834	((((((conduct\$3 copper) near5 (foil sheet layer)) and (etch\$3 pattern\$4)) and (via trench hole recess)) and (insulat\$3 dielectric)) and (pr photo?resist photoresist resist)) and (copper Cu aluminum Al)) and wir\$3 and resin) and (singulat\$3 dic\$3)	USPAT; US-PGPUB	2003/02/11 16:35
-	4670	((((((conduct\$3 copper) near5 (foil sheet layer)) and (etch\$3 pattern\$4)) and (via trench hole recess)) and (insulat\$3 dielectric)) and (pr photo?resist photoresist resist)) and (copper Cu aluminum Al)) and wir\$3 and resin) and circuit	USPAT; US-PGPUB	2003/02/11 16:36
-	4040	((((((conduct\$3 copper) near5 (foil sheet layer)) and (etch\$3 pattern\$4)) and (via trench hole recess)) and (insulat\$3 dielectric)) and (pr photo?resist photoresist resist)) and (copper Cu aluminum Al)) and wir\$3 and resin) and circuit) and (cover\$3 encapsulat\$3)	USPAT; US-PGPUB	2003/02/11 16:37

-	3307	(((((conduct\$3 copper) near5 (foil sheet layer)) and (etch\$3 pattern\$4)) and (via trench hole recess)) and (insulat\$3 dielectric)) and (pr photo?resist photoresist resist)) and (copper Cu aluminum Al)) and wir\$3) and resin) and circuit) and (cover\$3 encapsulat\$3)) and ((etch\$3 pattern\$4) near10 (copper Cu conduct\$3))	USPAT; US-PGPUB	2003/02/11 17:36
-	3307	(((((conduct\$3 copper) near5 (foil sheet layer)) and (etch\$3 pattern\$4)) and (via trench hole recess)) and (insulat\$3 dielectric)) and (pr photo?resist photoresist resist)) and (copper Cu aluminum Al)) and wir\$3) and resin) and circuit) and (cover\$3 encapsulat\$3)) and ((etch\$3 pattern\$4) near10 (copper Cu conduct\$3))) and wir\$3	USPAT; US-PGPUB	2003/02/11 17:36
-	2618	(((((conduct\$3 copper) near5 (foil sheet layer)) and (etch\$3 pattern\$4)) and (via trench hole recess)) and (insulat\$3 dielectric)) and (pr photo?resist photoresist resist)) and (copper Cu aluminum Al)) and wir\$3) and resin) and circuit) and (cover\$3 encapsulat\$3)) and ((etch\$3 pattern\$4) near10 (copper Cu conduct\$3))) and wir\$3) and bond\$3	USPAT; US-PGPUB	2003/02/11 17:39
-	2660	(((((conduct\$3 copper) near5 (foil sheet layer)) and (etch\$3 pattern\$4)) and (via trench hole recess)) and (insulat\$3 dielectric)) and (pr photo?resist photoresist resist)) and (copper Cu aluminum Al)) and wir\$3) and resin) and circuit) and (cover\$3 encapsulat\$3)) and ((etch\$3 pattern\$4) near10 (copper Cu conduct\$3))) and wir\$3) and (die bond\$3)	USPAT; US-PGPUB	2003/02/11 17:42